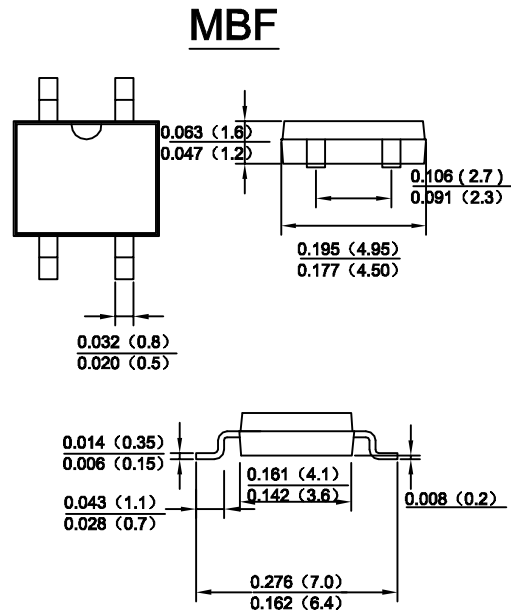


## Features

- Schottky Brrier Chip
- Low Power Loss,High Efficiency
- Ideally Suited for Automatic Assembly
- Surge Overload Rating to 30A Peak
- Plastic Case Material has UL Flammability Classification Rating 94V-0

## Mechanical Data

- Case: MB-F, molded plastic
- Terminals: plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting position: Any
- Marking: type number
- Lead Free: For RoHS / Lead Free Version,



dimensions in inches and (millimeters)

## Maximum Ratings and Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	KMB 12F	KMB 13F	KMB 14F	KMB 145F	KMB 15F	KMB 16F	KMB 18F	KMB 110F	KMB 115F	KMB 120F	KMB 125F	UNITS
Peak Repetitive Reverse Voltage	$V_{RRM}$	20	30	40	45	50	60	80	100	150	200	250	
RMS Reverse Voltage	$V_{R(RMS)}$	14	21	28	31	35	42	56	70	105	140	175	V
DC Blocking Voltage	$V_{DC}$	20	30	40	45	50	60	80	100	150	200	250	
Average Rectified Output Current ( Note1) @ $T_A = 90^{\circ}\text{C}$	$I_O$	1.0											A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	30											A
$I^2t$ Rating for Fusing ( $t < 8.3\text{ms}$ )	$I^2t$	3.735											$\text{A}^2\text{s}$
Forward Voltage per element @ $I_F = 1.0\text{AV}$	$V_{FM}$	0.55		0.7		0.85		0.90		0.92			V
Peak Reverse Current @ $T_A = 25^{\circ}\text{C}$ At Rated DC Blocking Voltage @ $T_A = 100^{\circ}\text{C}$	$I_{RM}$	0.1						0.05					mA
		10						5					
Typical Junction Capacitance per leg	$C_j$	28											pF
Typical Thermal Resistance per leg ( Note2)	$R_{\theta JA}$	75											$^{\circ}\text{C/W}$
Operating junction temperature range	$T_J$	-55 to +150											$^{\circ}\text{C}$
Operating and Storage Temperature Range	$T_{STG}$	-55 to +150											$^{\circ}\text{C}$

**Note:**

1. Mounted on aluminum substrate PC board with  $1.3\text{mm}^2$  solder pad.
2. Thermal REsistance From Junction to Ambient

FIG. 1- FORWARD CURRENT DERATING CURVE

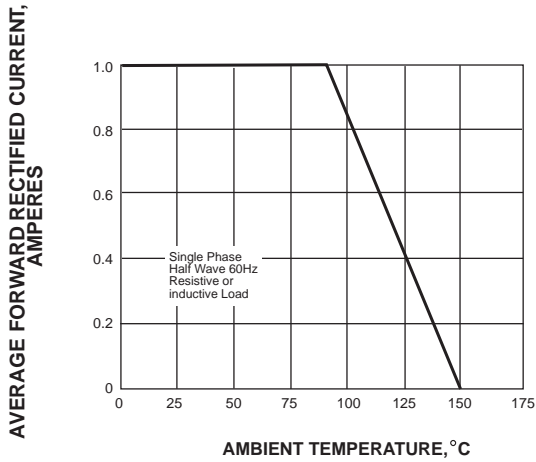


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

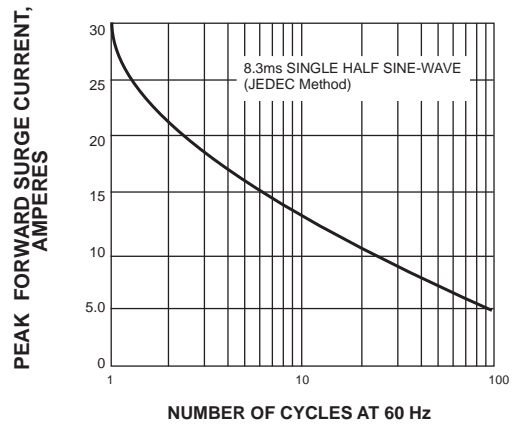


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

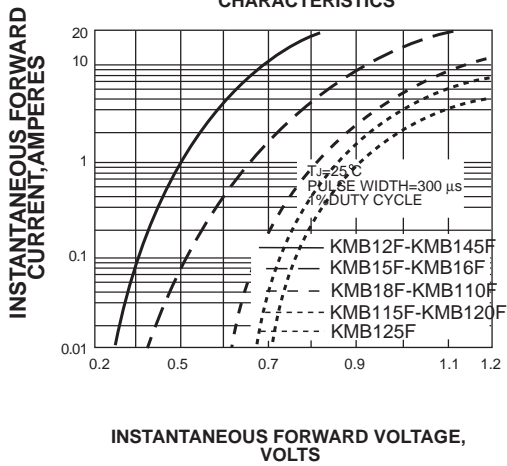


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

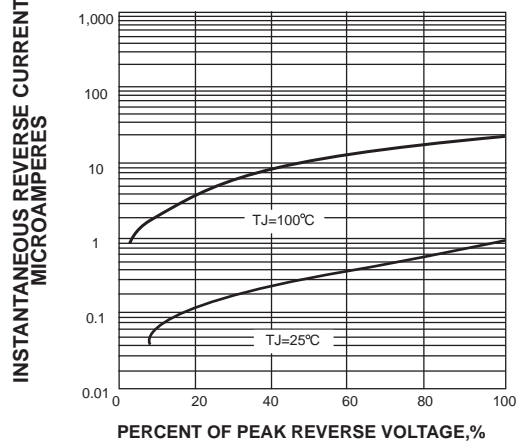


FIG. 5-TYPICAL TRANSIENT THERMAL IMPEDANCE

